

LED Ceramic Substrate



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陽昇應用材料(股)有限公司

Product Catalogue Taiwan 2013-14

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◆ Chip on Board –
COB LED Substrate

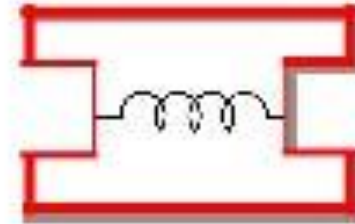
◆ Flash LED Substrate

◆ High Power LED Substrate

◆ COB – Sapphire

◆ Glass LED Substrate

CHEERING SUN
APPLIED MATERIALS CO.,LTD.



陶瓷載板：

利用自主研發之陶瓷加工技術及厚膜印刷燒結技術，可製造出各種用途之陶瓷載板。特別是有3D結構(雙面導通孔，立體圍繞壁...等等)之設計，可應用為LED, IC封裝載板，或電路保護元件之基板等用途。

Hybrid Ceramic Substrate：

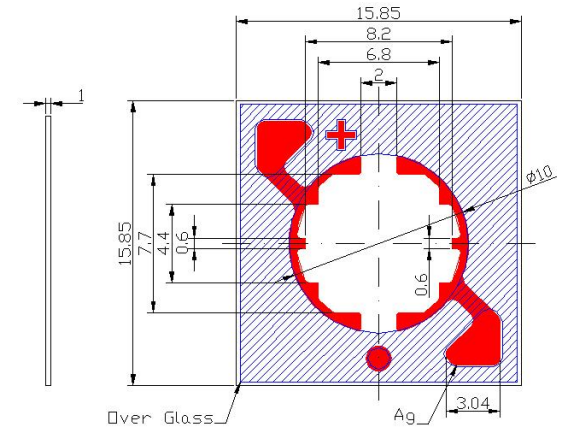
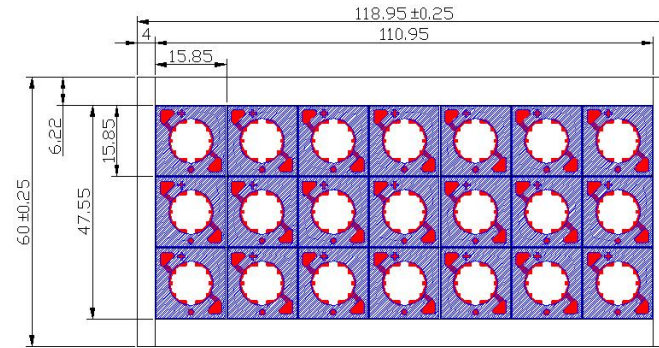
Using our self-developed R & D of ceramic processing skills and sintering thick film printing technology, we can produce a variety of hybrid ceramic substrate. Especially with the design of 3D structures for (Two-sided via-holes, Dam etc...), The substrate and other purposes can be applied to LED, IC package substrates, or circuit protection devices.



Products Specification and Dimension Parameter

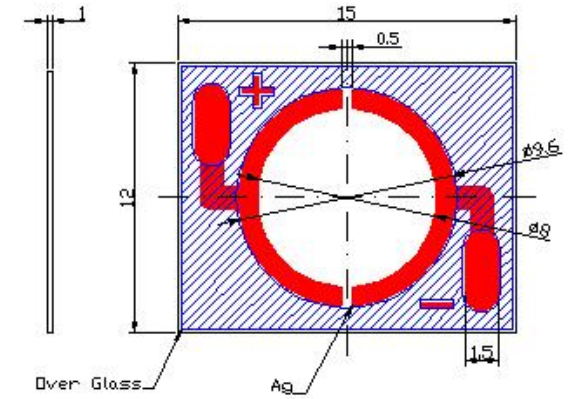
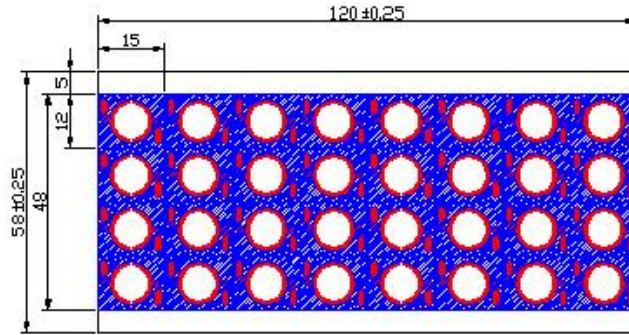
產品規格及尺寸參數

CL1515 – Array of sheet : 3 × 7= 21 pcs



高功率 - COB
96% 氧化铝 (Alumina)

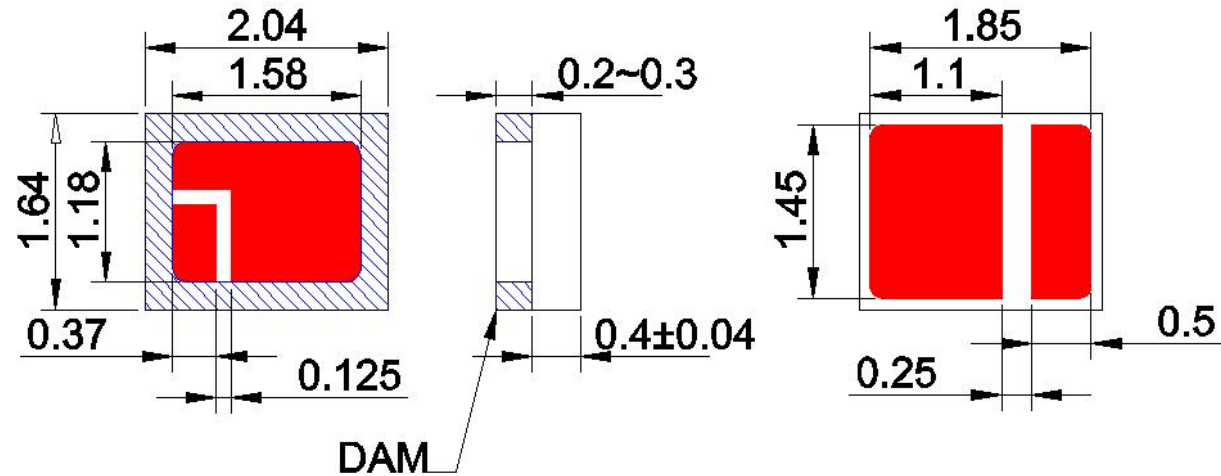
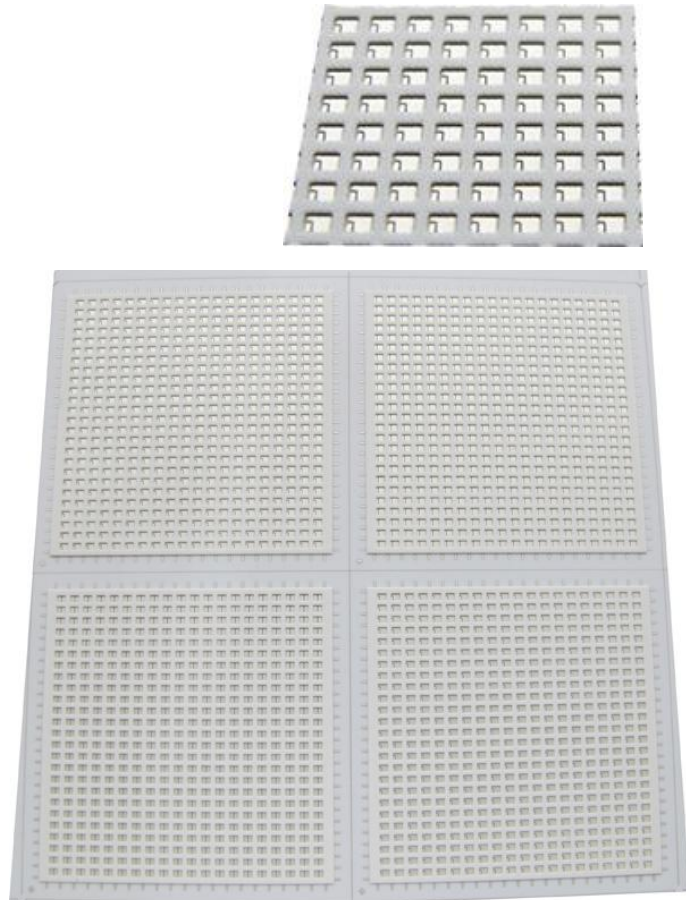
CL1215 – Array of sheet : 4 × 8= 32 pcs



高功率 - COB
96% 氧化铝 (Alumina)

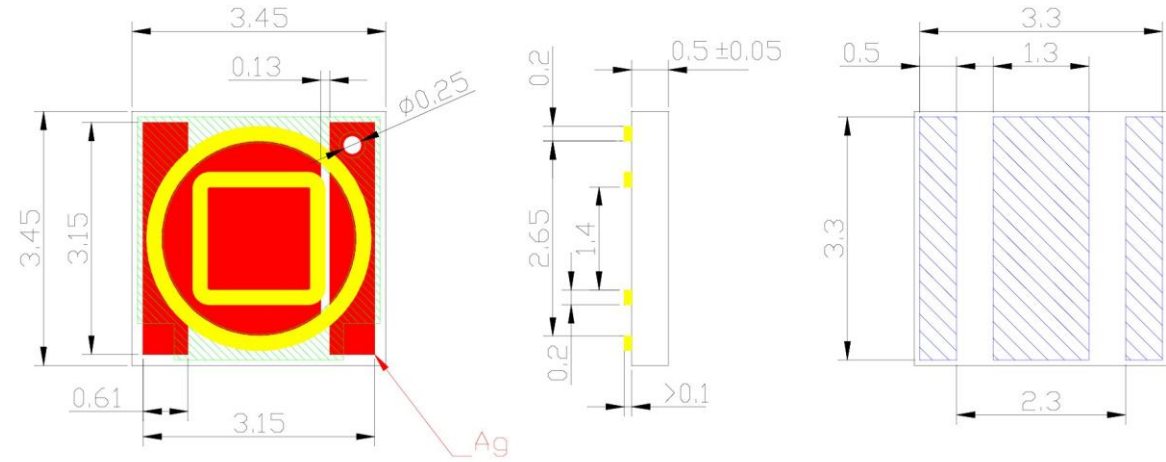
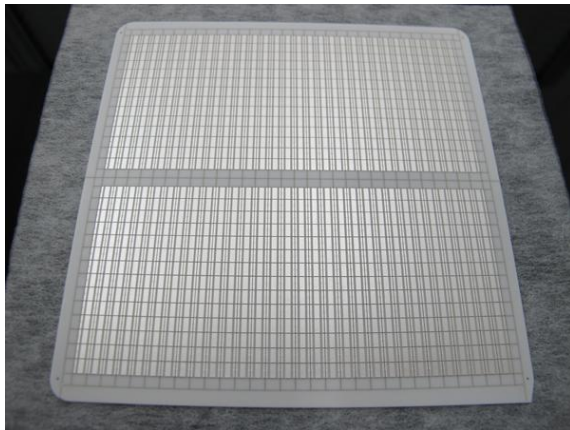
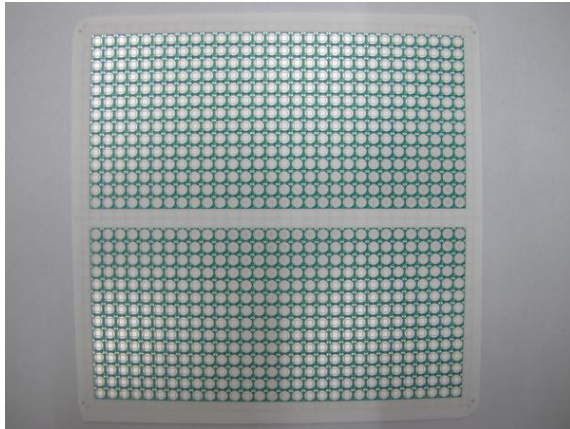


CL2016 – Array of sheet : 20 × 25= 500 pcs



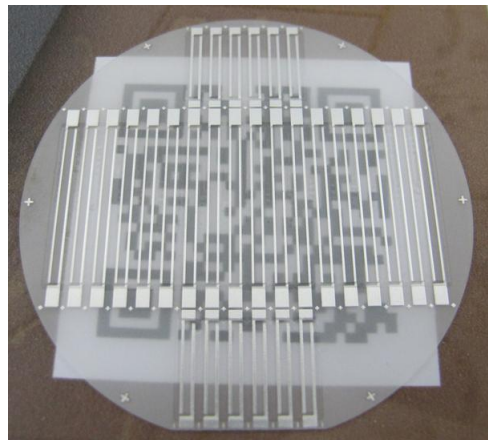
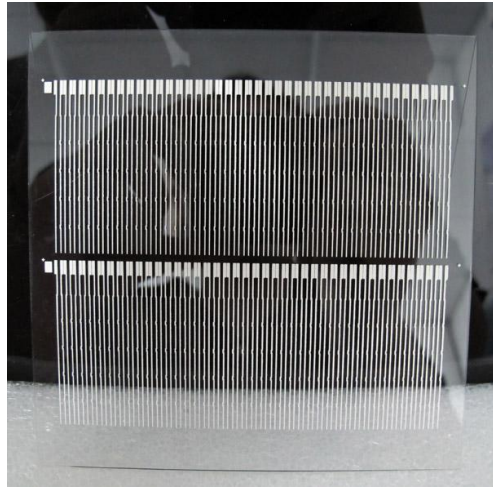
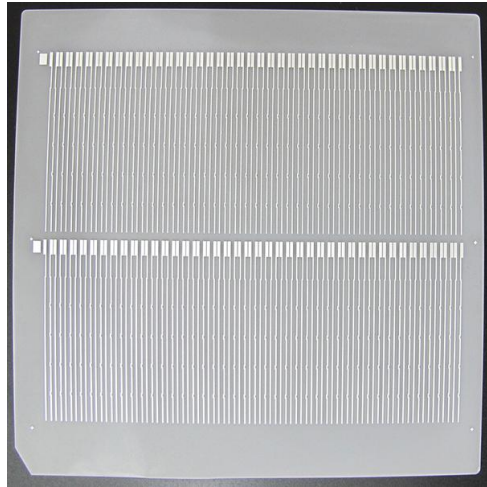
高功率 - 3D 環繞壁 Flash
96% 氧化鋁 (Alumina)
with 3D DAM

CL3535 – Array of sheet : $14 \times 30 = 420$ pcs



高功率 - 綠漆防焊 雙圍 3D 環繞壁
96% 氧化鋁 (Alumina)
with solder mask double-DAM

CL5000 – CLG5050



Specification	Conductive Layer	Substrate Material		
	Silver	Al2O3 (99.9%)	Glass	Sapphire
5000	V	V		V
5050	V		V	

透光陶瓷基板 or 玻璃基板



Product materials performance list & Design Rules for LED Carrier

產品材料性能表 & 設計規範

Product materials performance list :

Specification	Substrate Material		Conductive Layer	Coating Layer			Electrode Type		
	Al2O3 (96%)	ALN	Silver	Material			2-electrode	Multi-electrode	Thermal - Electric Separation
				Glass	Epoxy	Silicon			
1515	V		V	V	V	V			
1215	V		V	V	V	V			
2016	V	△	V	V	V	V			
3535	V	△	V	V	V		V	V	

△ : pending

Design Rules for LED Chip Carrier :

	Item	Standard min.(Unit : μm)	Premium min.(Unit : μm)
1	Via diameter	250	150
2	Via – via pitch	400	250
3	Line width	150	75
4	Line spacing	150	100
5	Distance between pattern edge and substrate edge	150	100

Via Hole Spec apply to substrate thickness less than 1mm



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